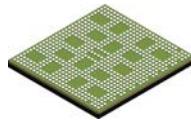


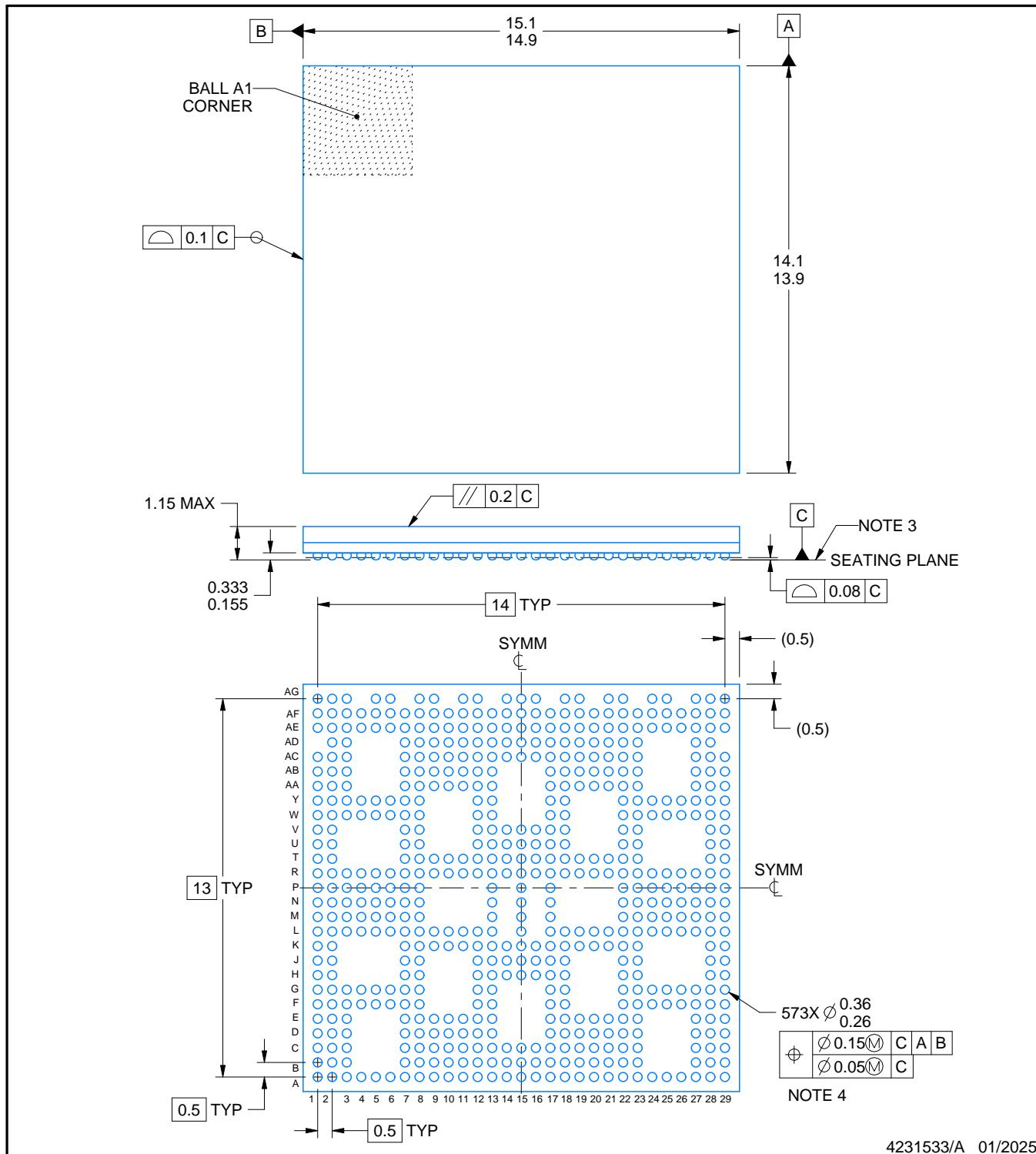
# PACKAGE OUTLINE

**APE0573A**



**FCCSP - 1.15 mm max height**

PLASTIC BALL GRID ARRAY



**NOTES:**

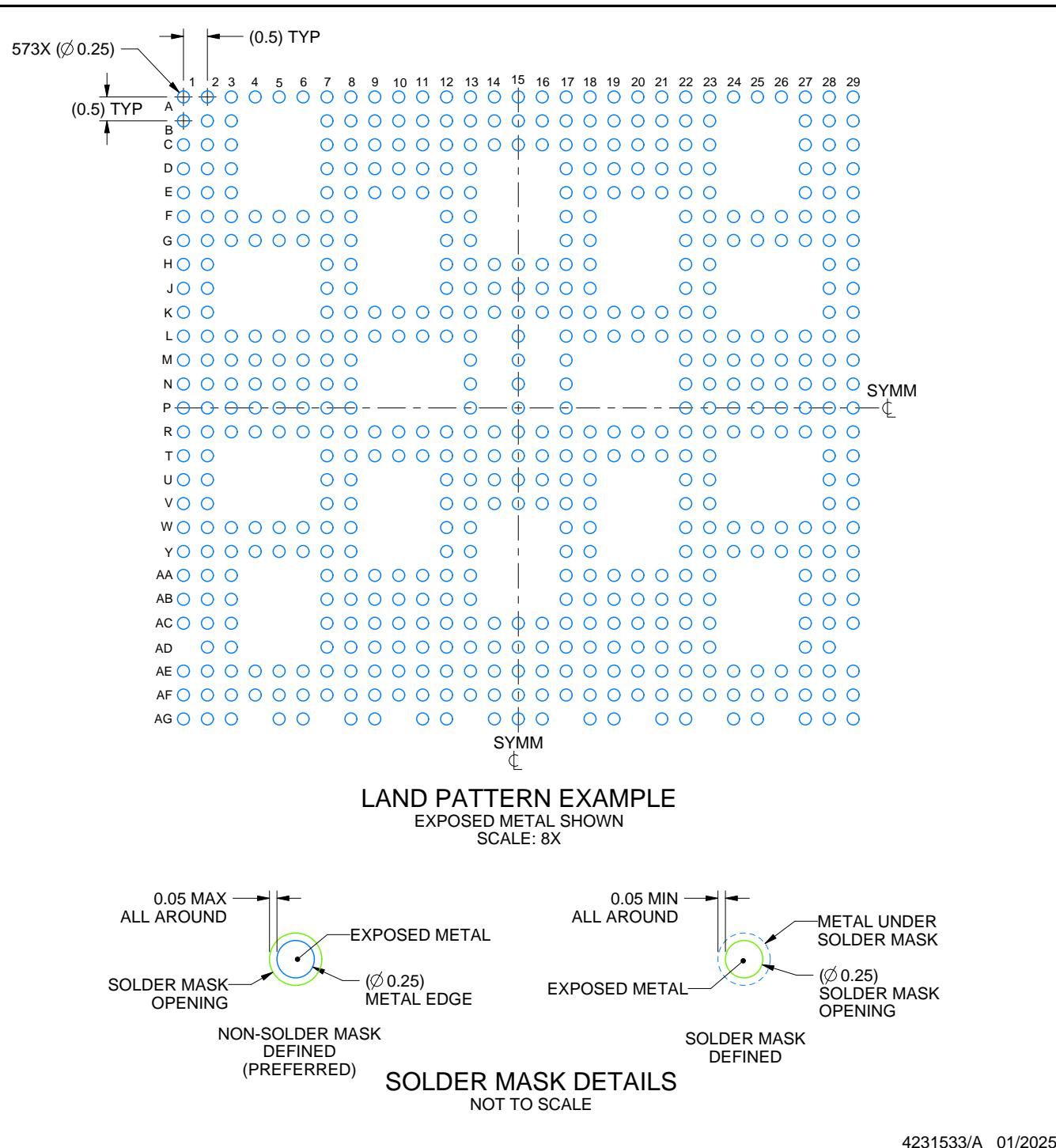
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Primary datum C and seating plane are defined by the spherical crowns of the solder balls.
4. Dimension is measured at the maximum solder ball diameter, post reflow, parallel to primary datum C.

## EXAMPLE BOARD LAYOUT

**APE0573A**

## FCCSP - 1.15 mm max height

## PLASTIC BALL GRID ARRAY



#### NOTES: (continued)

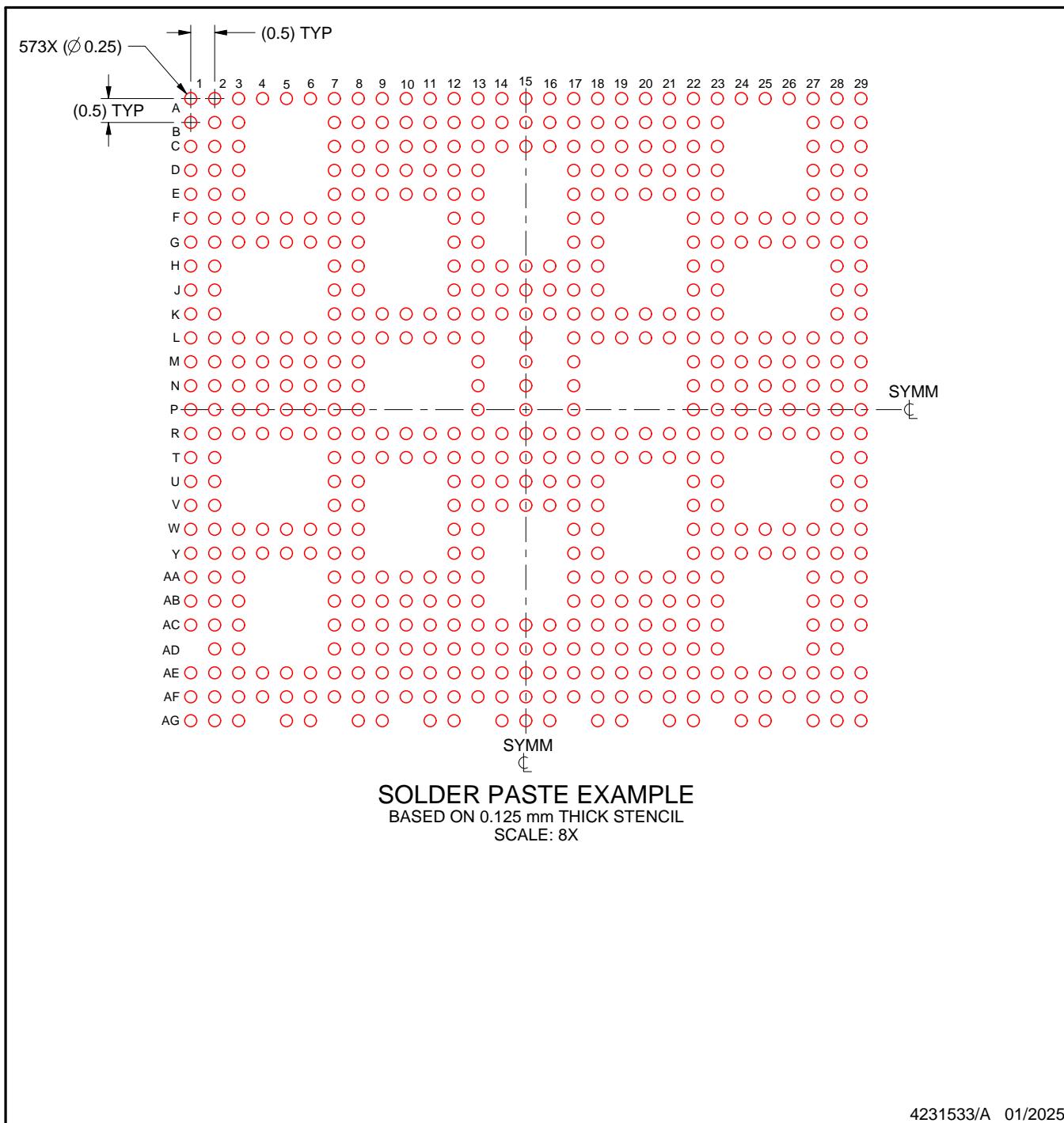
5. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRAA99 ([www.ti.com/lit/spraa99](http://www.ti.com/lit/spraa99)).

# EXAMPLE STENCIL DESIGN

**APE0573A**

**FCCSP - 1.15 mm max height**

PLASTIC BALL GRID ARRAY



NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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